Final Product Change Notification — 201404007F01

Issue Date: 18-Apr-2014
Effective Date: 17-Jul-2014

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Change Category

[X] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Change of bond wire from Au to Cu, new mold compound and lead frame supplier inSOT23

Details of this Change

Scheduled changes affect product types PMV32UP, PMV33UPE, PMV48XP, PMV50UPE, and PMV65XP in SOT23 package only.

The bond wire material will be changed from gold (Au) to copper (Cu). A new mold compound and lead frame supplier will be introduced for copper wire products. Implementation of change to copper wire as given by planned first shipment date below.

Old product: wire material is Au (with currently used mold compound and lead frame supplier)
Changed product: wire material is Cu (with new mold compound and lead frame supplier)

Additional change affecting only product types PMV32UP and PMV48XP is the implementation of dies with reduced thickness of 145 µm in addition to the existing dies. For details see attached SQR.

The design and materials of other components like die and die attach remain unchanged. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 30-May-2014.

Production

Planned first shipment 28-Jul-2014

Impact

No impact to the products' functionality anticipated.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 18-May-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name   GA Customer Support
e-mail address   DiscrQA.Helpdesk.GA-Products@nxp.com
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